United States Patent [19]

Armstrong

[11] **Patent Number: Des. 316,251**

[45] **Date of Patent: ** Apr. 16, 1991**

[54] **IN-LINE SEMICONDUCTOR PACKAGE**

[75] Inventor: **David Y. Armstrong**, San Diego, Calif.

[73] Assignee: **Mosaic Semiconductor, Inc.**, San Diego, Calif.

[**] Term: **14 Years**

[21] Appl. No.: **287,982**

[22] Filed: **Dec. 19, 1988**

[52] **U.S. Cl.** **D13/182**

[58] **Field of Search** D13/182, 147; 361/403, 361/404, 405; 174/52.2, 52.4; 357/70, 72; 437/209

[56] **References Cited**

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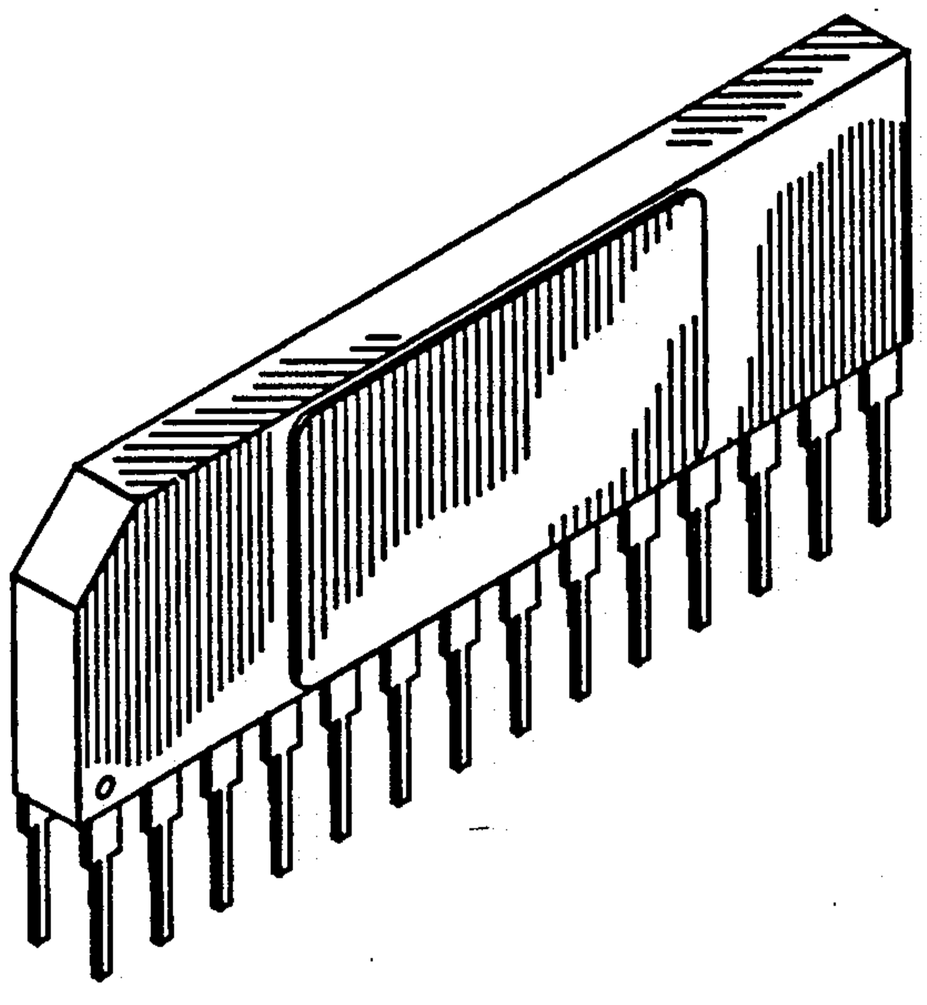
Primary Examiner—Susan J. Lucas
Assistant Examiner—Joel Sincavage
Attorney, Agent, or Firm—Knobbe, Martens, Olson & Bear

[57] **CLAIM**

The ornamental design for a in-line semiconductor package, as shown and described.

DESCRIPTION

FIG. **1** is a top, front and left side perspective view of an in-line semiconductor package showing my new design;
FIG. **2** is a top plan view thereof;
FIG. **3** is a front elevational view thereof;
FIG. **4** is a bottom plan view thereof;
FIG. **5** is a rear elevational view thereof;
FIG. **6** is a left side elevational view thereof;
FIG. **7** is a right side elevational view thereof;
FIG. **8** is a top, front and left side perspective view of an in-line semiconductor package showing a second embodiment of my new design;
FIG. **9** is a top plan view thereof;
FIG. **10** is a front elevational view thereof;
FIG. **11** is a bottom plan view thereof;
FIG. **12** is a rear elevational view thereof;
FIG. **13** is a right side elevational view thereof, the left side being a mirror image;
FIG. **14** is a top, front and left side perspective view of an in-line semiconductor package showing a third embodiment of my new design;
FIG. **15** is a bottom, left and rear perspective view thereof;
FIG. **16** is a top, front and left side perspective view of an in-line semiconductor package showing a fourth embodiment of my new design;
FIG. **17** is a bottom, left and rear perspective view thereof;
FIG. **18** is a top, front and left side perspective view of an in-line semiconductor package showing a fifth embodiment of my new design;
FIG. **19** is a bottom, left and rear perspective view thereof;
FIG. **20** is a right side elevational view of the third, fourth and fifth embodiments of my new design.



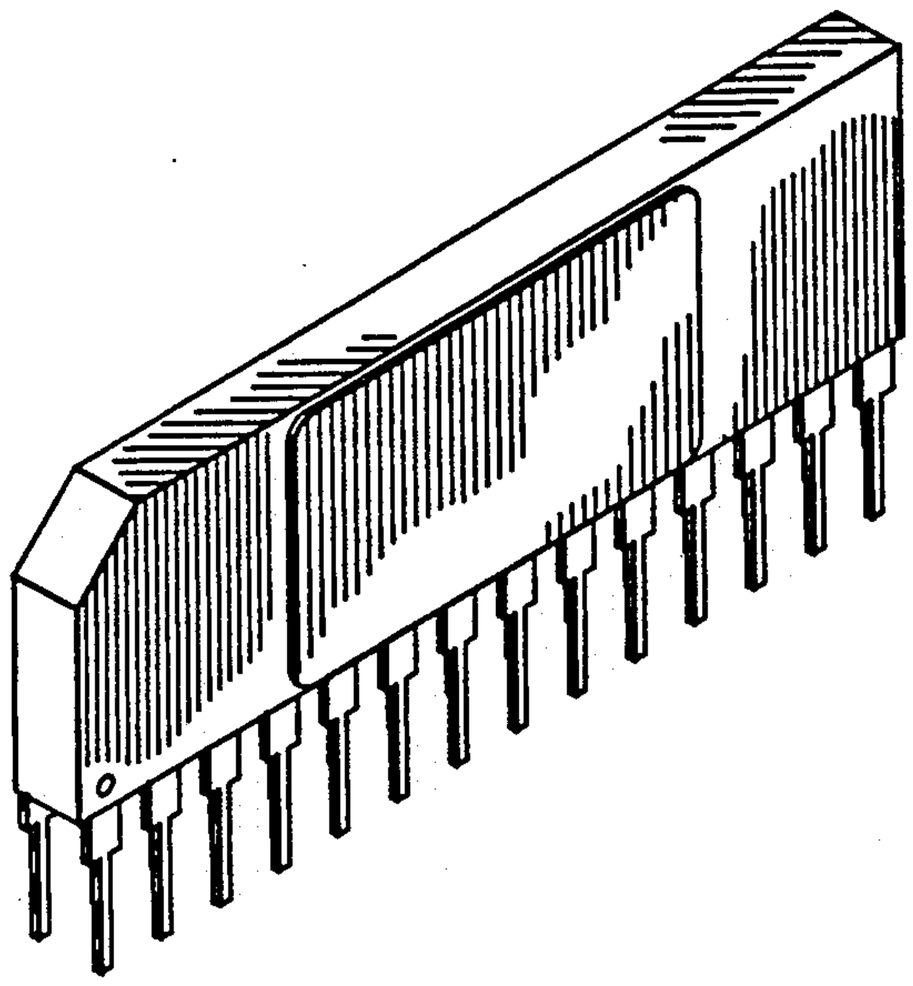


FIG. 1

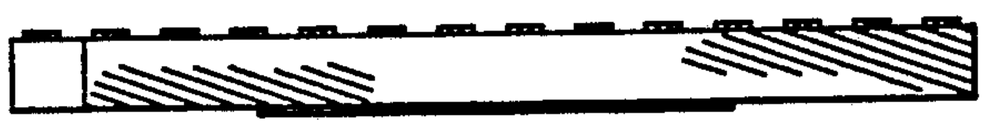


FIG. 2

FIG. 6

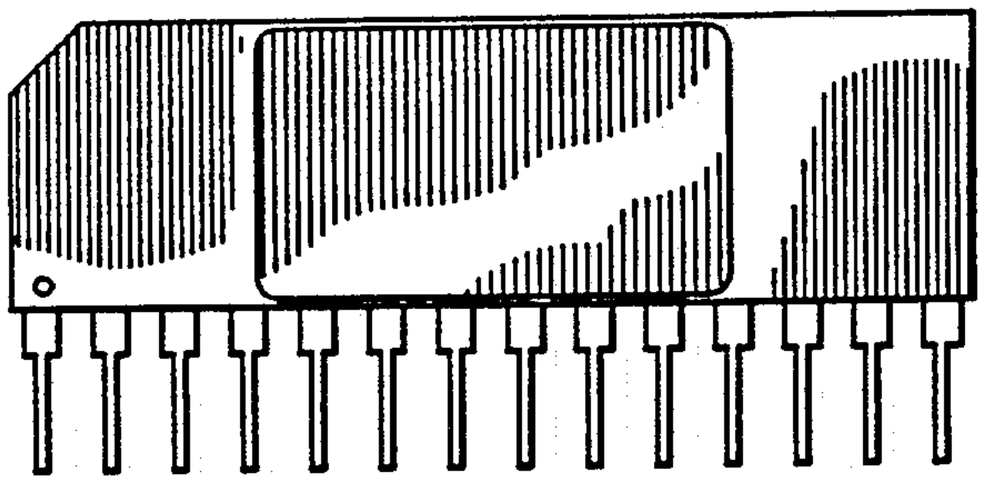


FIG. 3

FIG. 7

FIG. 4

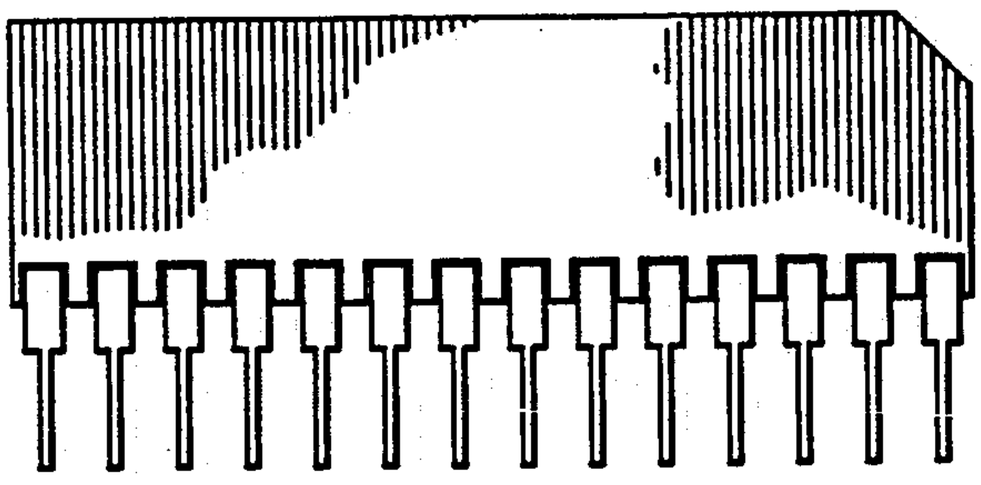


FIG. 5

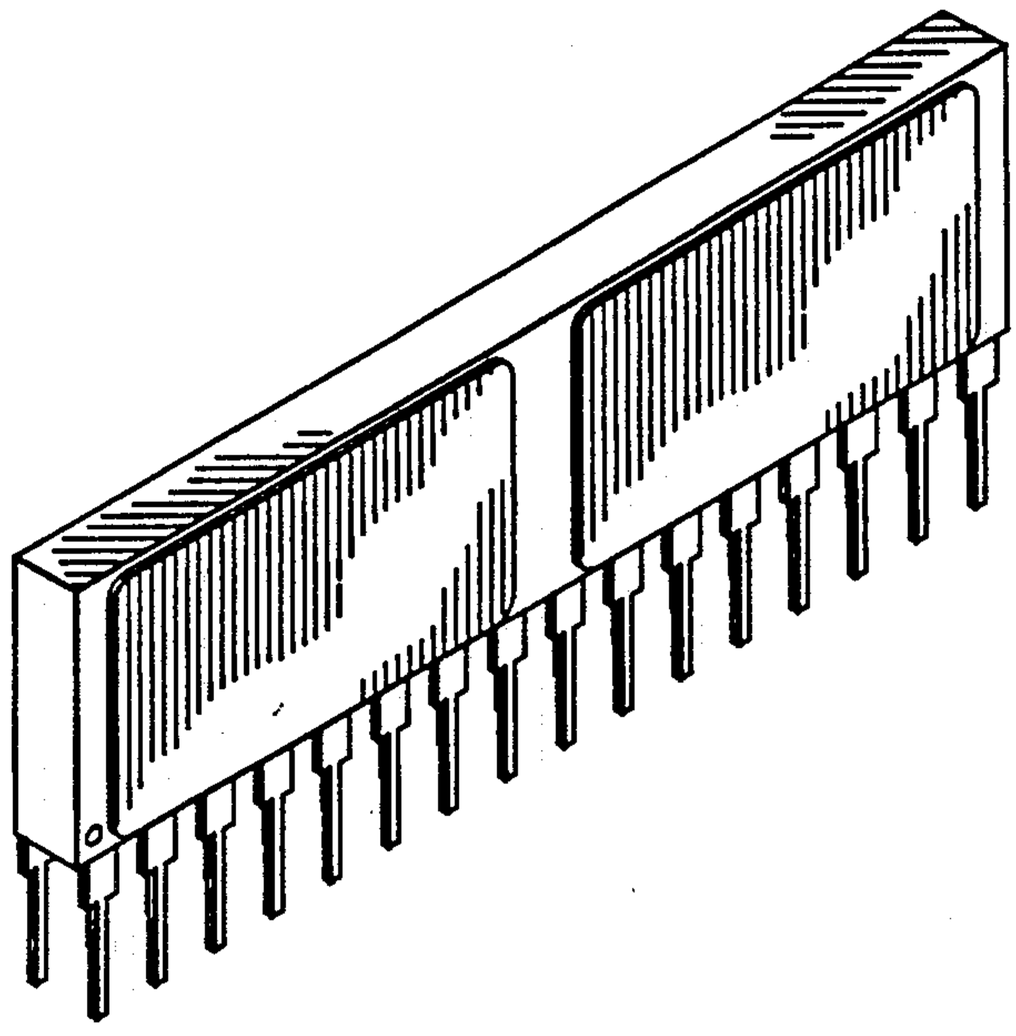


FIG. 8

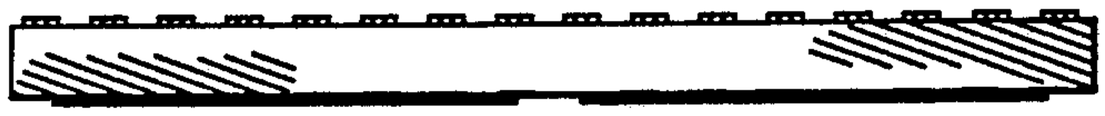


FIG. 9

FIG. 13

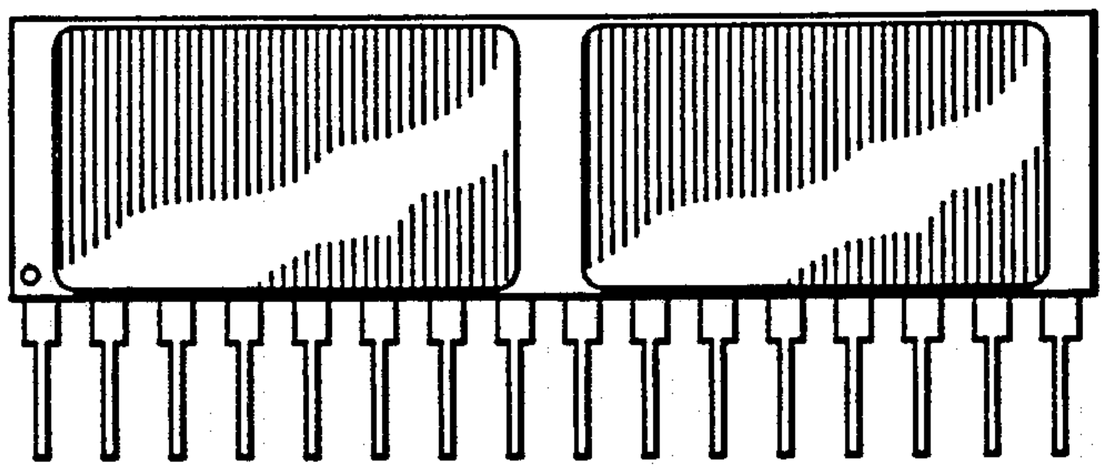


FIG. 10

FIG. 11

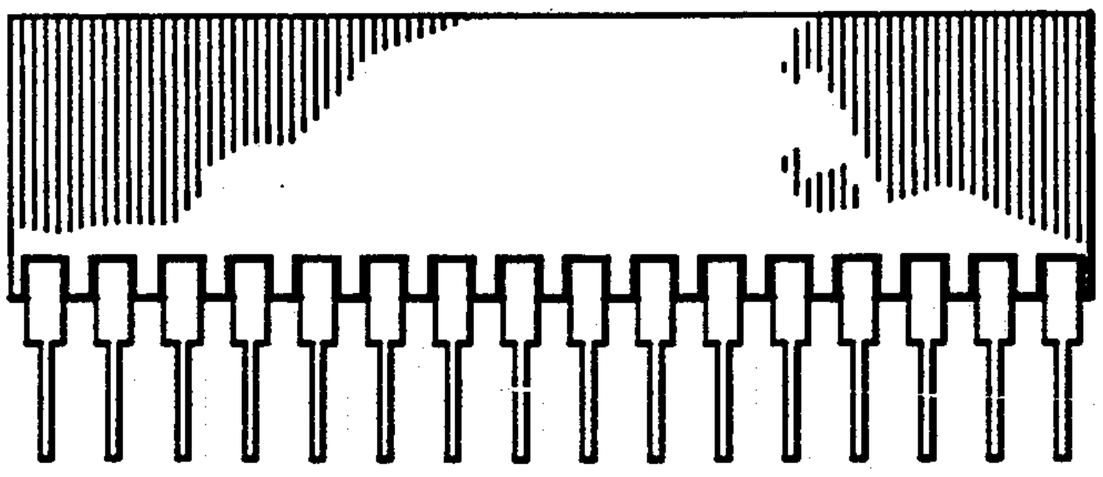


FIG. 12

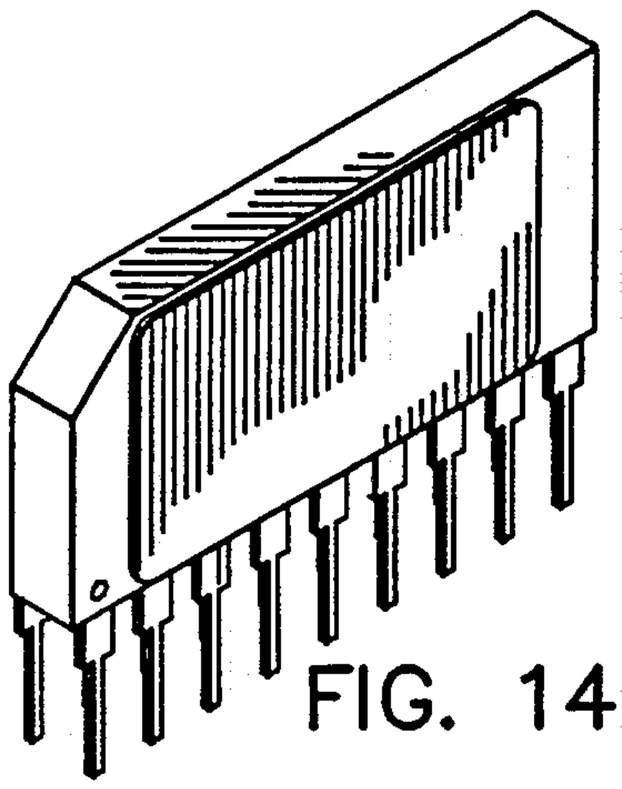


FIG. 14

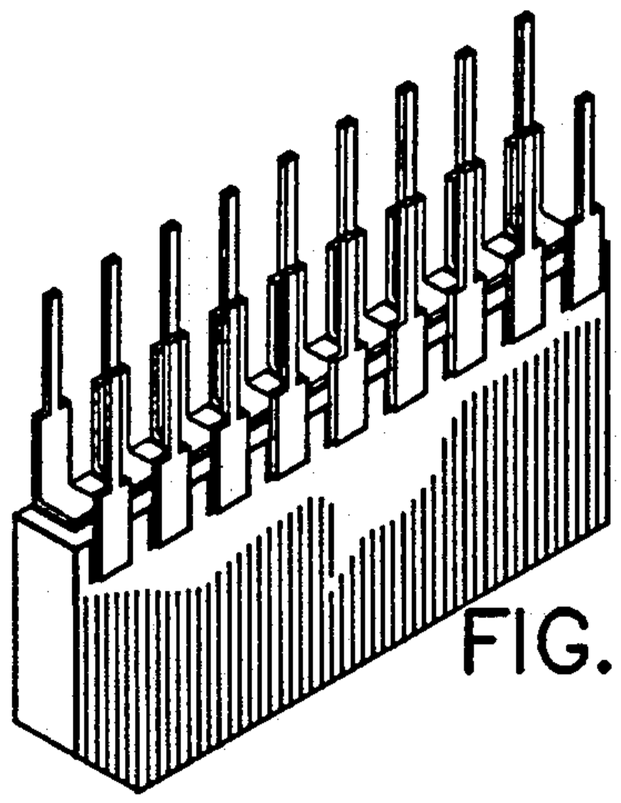


FIG. 15

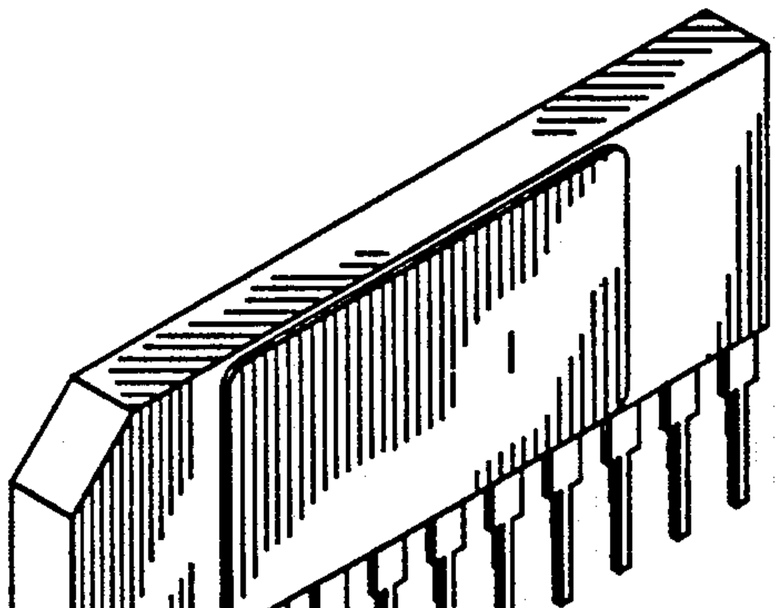


FIG. 16

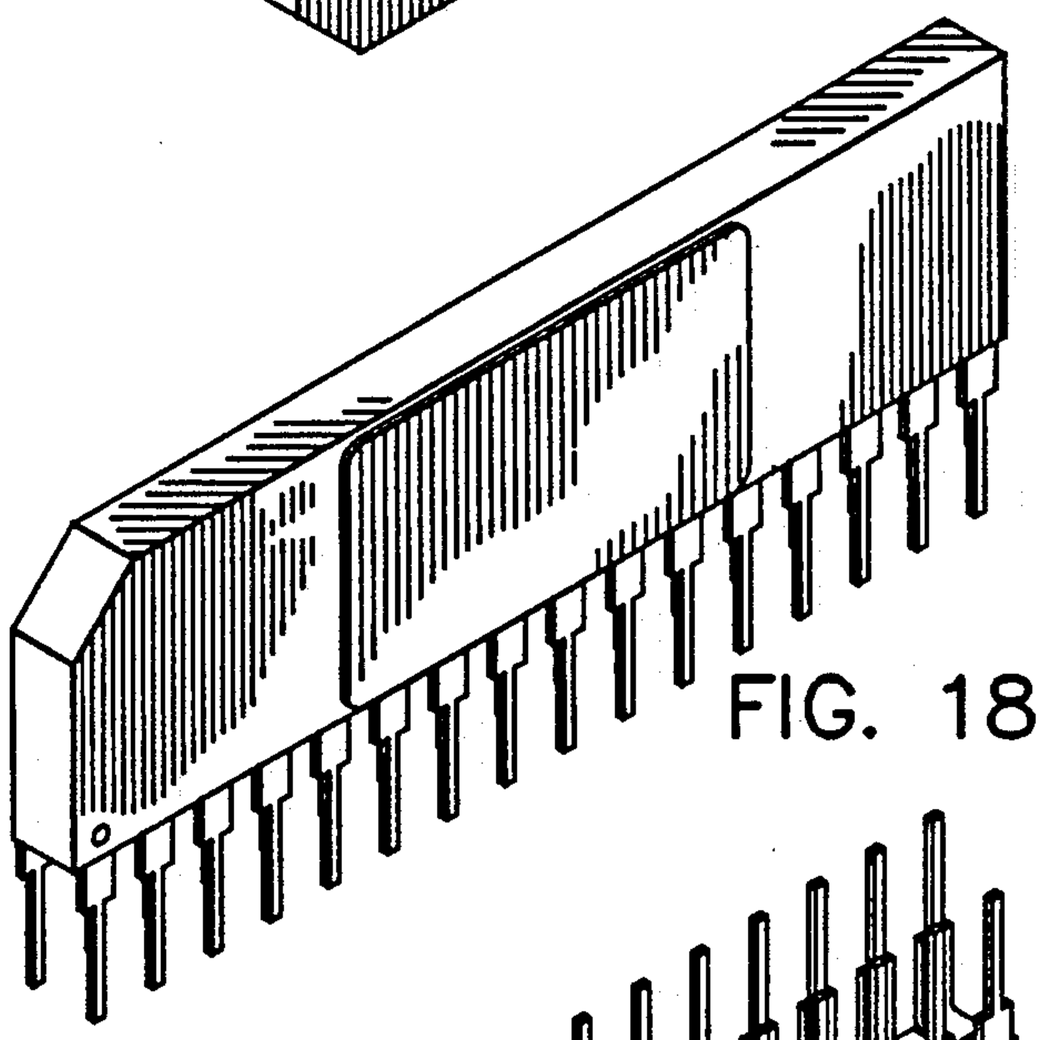


FIG. 18

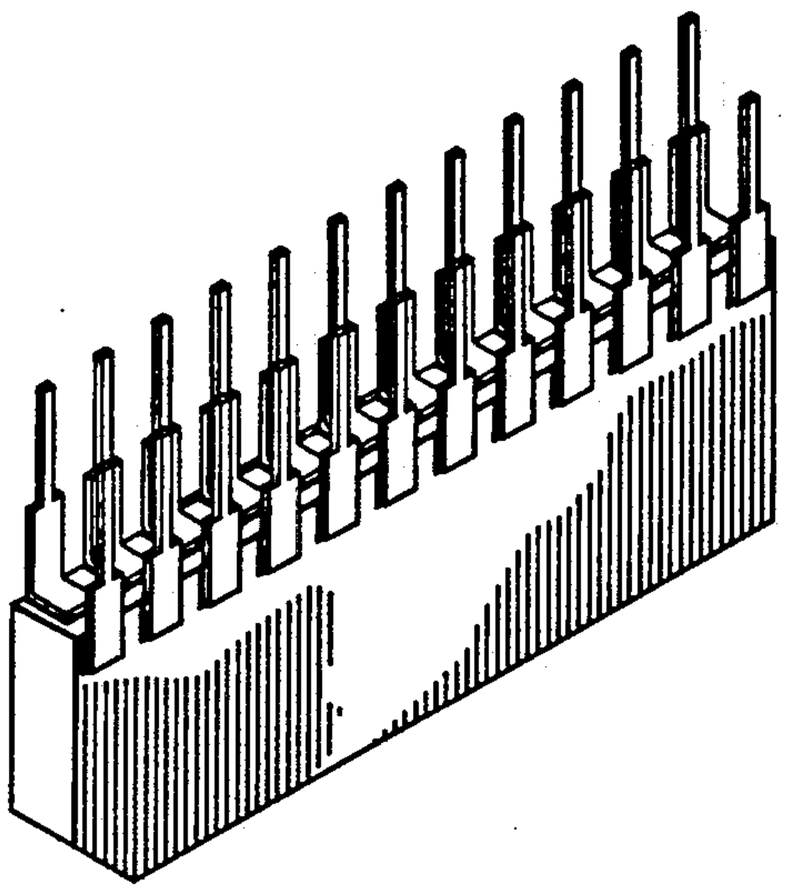


FIG. 17

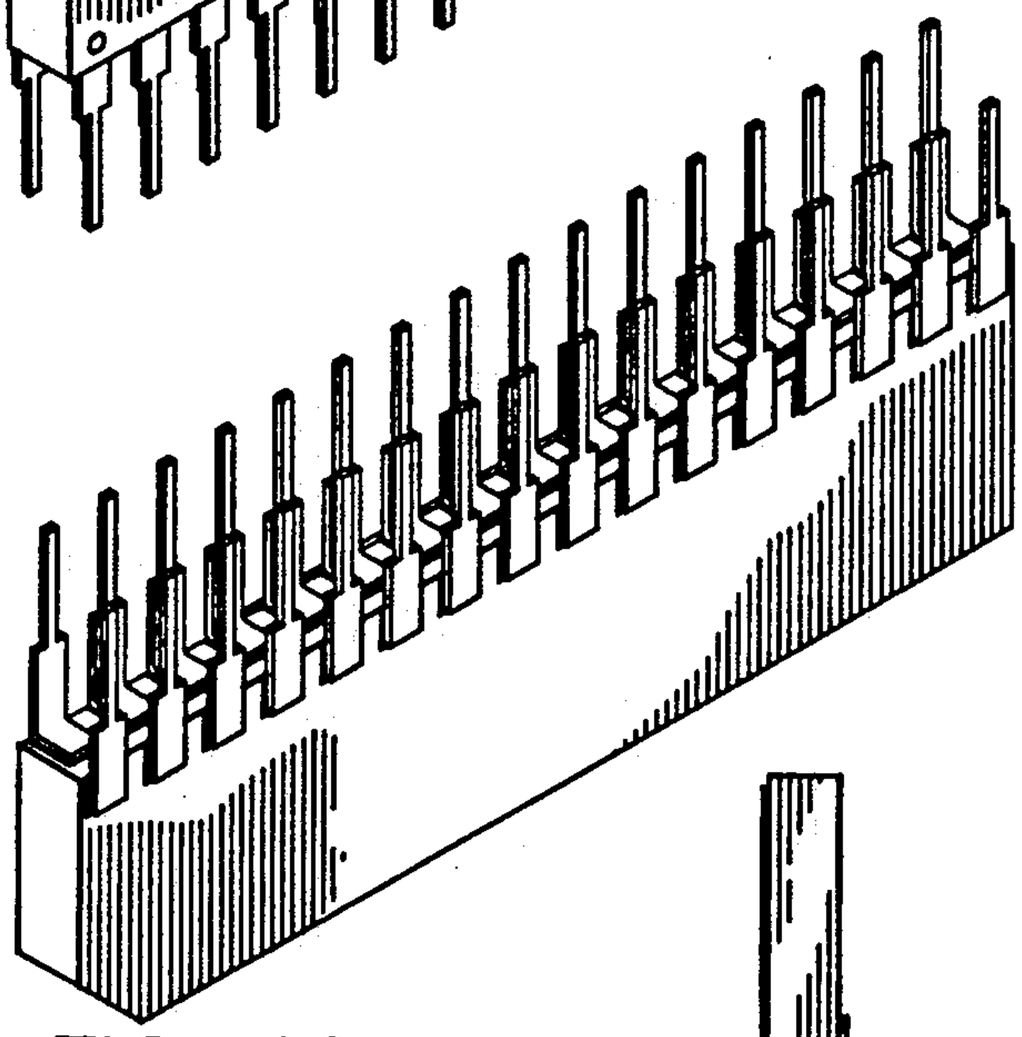


FIG. 19

FIG. 20